

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2001-298277

(43)Date of publication of application : 26.10.2001

(51)Int.Cl.

H05K 5/02  
B05D 7/14  
B05D 7/24  
B29C 45/14  
// B29K 55:02  
B29K 59:00  
B29K 67:00  
B29K 69:00  
B29K 77:00

(21)Application number : 2000-111315

(71)Applicant : TAISEI PLAS CO LTD

(22)Date of filing : 12.04.2000

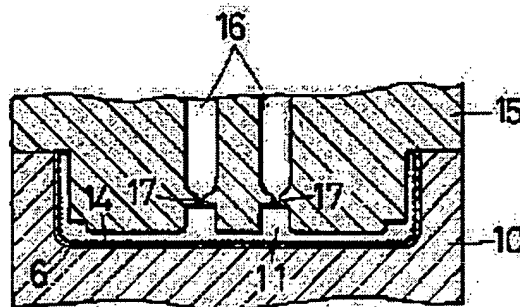
(72)Inventor : NARUTOMI MASANORI  
ANDO NAOKI  
OTOMO KAZUO

## (54) HOUSING FOR ELECTRONIC APPARATUS AND METHOD OF MANUFACTURE

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To obtain a housing for electronic apparatus combining the merits of metallic housing and synthetic resin housing and can be mass produced with high productivity in which the shape and structure can be designed freely.

**SOLUTION:** At least epoxy resin based paint is applied to a metal frame 6, cured and pretreated and then inserted into an injection molding die for injecting a rib 7. Surface of the metal frame 6 is filled with thermosetting synthetic resin by injection molding and the rib 7 is molded. The housing of a molded case cover 3 where the metal frame 6 and the thermosetting synthetic resin rib 7 are bonded integrally makes the most use of the features of metal in view points of strength and design of external view and the housing can have intricate internal shape and structure.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or

application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office